



Revision History

Rev.	ECN No.	Description of Change	Date	Appvd By
A	23991	RTP, update to new format, note changes	01-14-02	K. Lohrmeyer
B	28408	Add -07ACM	07-08-04	D. Fitzgerald
C	28614	Update performance curves	08-24-04	K. Lohrmeyer
D	30745	Add -08ACM	02-10-06	D. Fitzgerald
E	32303	Add -09ACM	02-13-07	D. Fitzgerald
F	32339	Add -10ACM	02-20-07	D. Fitzgerald
G	33200	Add -11ACM	09-11-07	D. Fitzgerald
H	33395	Change to DOE Elements	11-01-07	D. Fitzgerald
J	33940	Update Note 8	03-19-08	D. Fitzgerald
K	34672	Add -21ACM	08-28-08	S. Perkins
L	34725	Add RoHS Note	09-19-08	J. Pitzer
M	38059	Add -03ACM	06-17-10	S. Perkins
N	41576	Change RoHS compliance on note 9	02-27-12	J. Pitzer
P	41944	Add -22ACM	04-12-12	D. Fitzgerald
R	44404	Add -23ACM	06-17-13	D. Fitzgerald

Document Approval

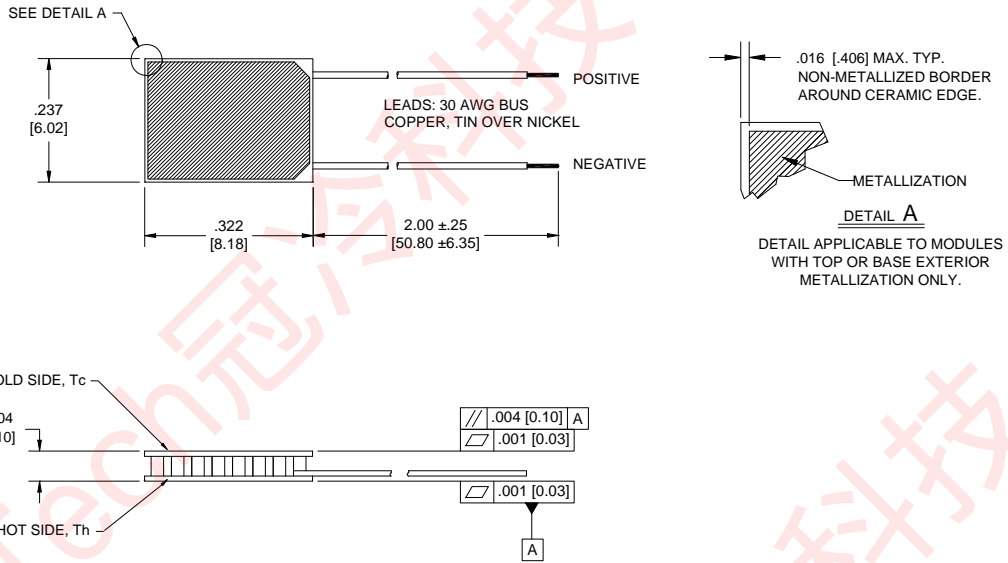
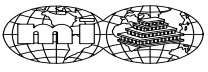
Next Assy

Used On

Originator:	K. Lohrmeyer	Date:	08-09-01
Dftg Check:	R. Narvaez	Date:	08-09-01
Prgm Mngr:		Date:	
Engr Mngr:	S. Thomas	Date:	07-07-04
Mfrg Mngr:	J. Ham	Date:	09-05-07
Quality:	J. Hunt	Date:	07-07-04

SP5255

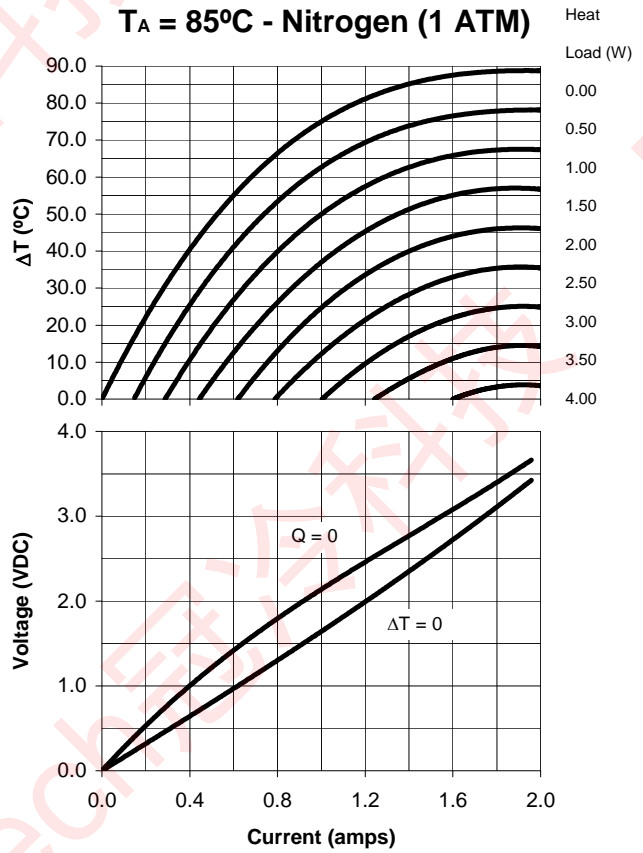
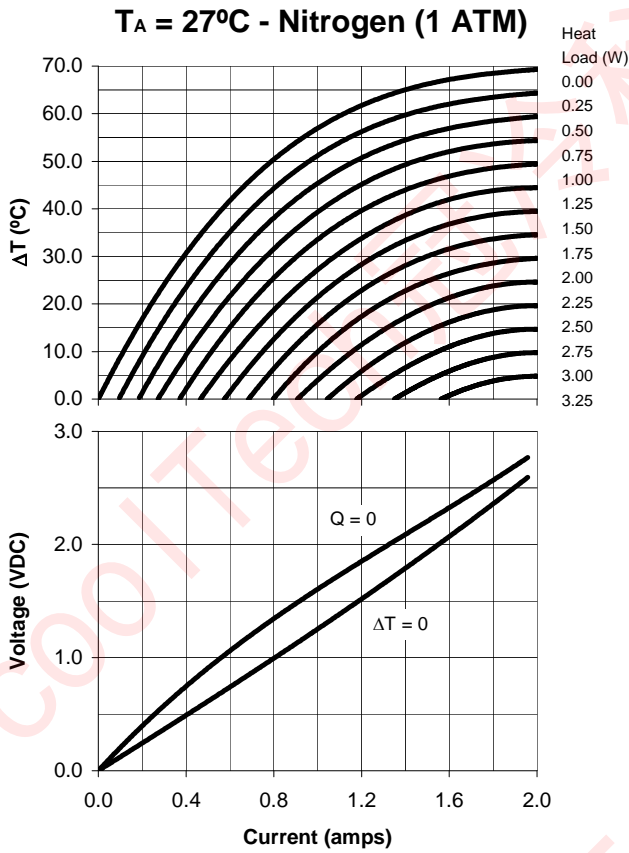
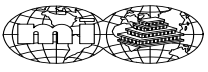
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1. Device exterior surfaces:
 - 03ACM: Bare Ceramic.
 - 13ACM and -14ACM: Gold flash (4-10 microinches).
 - 15ACM and -06ACM: Top ceramic tinned w/138°C solder and base ceramic tinned w/183°C solder.
 - 16ACM: Top and base exterior tinned with 146°C solder.
 - 17ACM, -20ACM and -11ACM: Top and base exterior tinned with 138°C solder.
 - 18ACM: Base exterior tinned with 183°C solder.
 - 19ACM: Top and base exterior tinned with 138°C solder to a maximum thickness of 50 microns.
 - 21ACM: Top and base exterior tinned with 117°C solder.
 - 22ACM: Base exterior tinned with 138°C solder and top exterior tinned with 117°C solder.
2. Dimensions include metallization when applicable.
3. Maximum operating temperature is 85°C.
4. Maximum process temperature is 220°C.
5. Dimensions within [] are in millimeters.
6. Edges may be scribed and snapped and may display irregularities within the stated tolerances.
7. Ceramic material: Aluminum Oxide
8. -14ACM only: Leads are insulated with 30 AWG Teflon sleeving 1.75 ± .125 inch long. Red sleeving indicates positive lead and black sleeving indicates negative lead.
9. -03ACM, -11ACM, -13ACM, -16ACM, -17ACM, -19ACM, -21ACM, -22ACM: RoHS EU Compliant.
10. -23ACM Bare Ceramic, sealed with RTV and leads are insulated with 30 AWG Teflon sleeving 1.75 ± .125 inch long. Red sleeving indicates positive lead and black sleeving indicates negative lead.

UNLESS OTHERWISE SPECIFIED	
- DIMENSIONS ARE IN INCHES, AND WITHIN [] ARE IN MILLIMETERS.	- DIMENSION LIMITS APPLY BEFORE FINISH PROCESSES
- GENERAL TOLERANCES: DECIMALS .XX= ±.01, .XXX= ±.005, .XXXX= ±.0005, ANGLES ± 2° FINISH 125	- REMOVE ALL BURRS AND SHARP EDGES .020 MAX - FILLET RADIUS .018 MAX - INTERPRET DRAWING PER ANSI Y14.5M

SP5255-03ACM	TEM Assembly, No External Metallization
SP5255-06ACM	TEM Assembly, 138°C/183°C Tinning
SP5255-11ACM	TEM Assembly, 138°C Exterior Tinning, Gold Plated Leads
SP5255-13ACM	TEM Assembly, Metallized Exterior, Gold Flash, Thin Ni, Etch Sonic
SP5255-14ACM	TEM Assembly, Gold Flash, Wire Sleeving, Thin Ni, Etch Sonic
SP5255-15ACM	TEM Assembly, 138°C/183°C Tinning, Thin Ni, Etch Sonic
SP5255-16ACM	TEM Assembly, 146°C Exterior Tinning, Thin Ni, Etch Sonic
SP5255-17ACM	TEM Assembly, 138°C Exterior Tinning, Thin Ni, Etch Sonic
SP5255-18ACM	TEM Assembly, 183°C Base Tinning Only, Thin Ni, Etch Sonic
SP5255-19ACM	TEM Assembly, 138°C Exterior Tinning, 50 microns max, Thin Ni, Etch Sonic
SP5255-20ACM	TEM Assembly, 138°C Exterior Tinning, Gold Plated Leads, Thin Ni, Etch Sonic
SP5255-21ACM	TEM Assembly, 117°C Exterior Tinning, Thin Ni, Etch Sonic
SP5255-22ACM	TEM Assembly, 138°C Base Exterior Tinning, 117°C Top Exterior Tinning
SP5255-23ACM	TEM Assembly, No External Metallization, Wire Sleeving, Sealed with RTV



TYPICAL PERFORMANCE	
Environment : Nitrogen (1 ATM)	
T _A (C) :	27
V _{MAX} (VDC) :	2.70
ΔT_{MAX} (C) :	69.0
I _{MAX} (amps) :	1.9
Q _{MAX} (W) :	3.5
ACR (Ω) :	1.20

TYPICAL PERFORMANCE	
Environment : Nitrogen (1 ATM)	
T _A (C) :	85
V _{MAX} (VDC) :	3.40
ΔT_{MAX} (C) :	89.0
I _{MAX} (amps) :	1.8
Q _{MAX} (W) :	4.1
ACR (Ω) :	-

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SP5255-06ACM	TEM Assembly, 138°C/183°C Tinning
SP5255-11ACM	TEM Assembly, 138°C Exterior Tinning, Gold Plated Leads
SP5255-13ACM	TEM Assembly, Metallized Exterior, Gold Flash, Thin Ni, Etch Sonic
SP5255-14ACM	TEM Assembly, Gold Flash, Wire Slewing, Thin Ni, Etch Sonic
SP5255-15ACM	TEM Assembly, 138°C/183°C Tinning, Thin Ni, Etch Sonic
SP5255-16ACM	TEM Assembly, 146°C Exterior Tinning, Thin Ni, Etch Sonic
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SP5255-21ACM	TEM Assembly, 117°C Exterior Tinning, Thin Ni, Etch Sonic
SP5255-22ACM	TEM Assembly, 138°C Base Exterior Tinning, 117°C Top Exterior Tinning
SP5255-23ACM	TEM Assembly, No External Metallization, Wire Slewing, Sealed with RTV